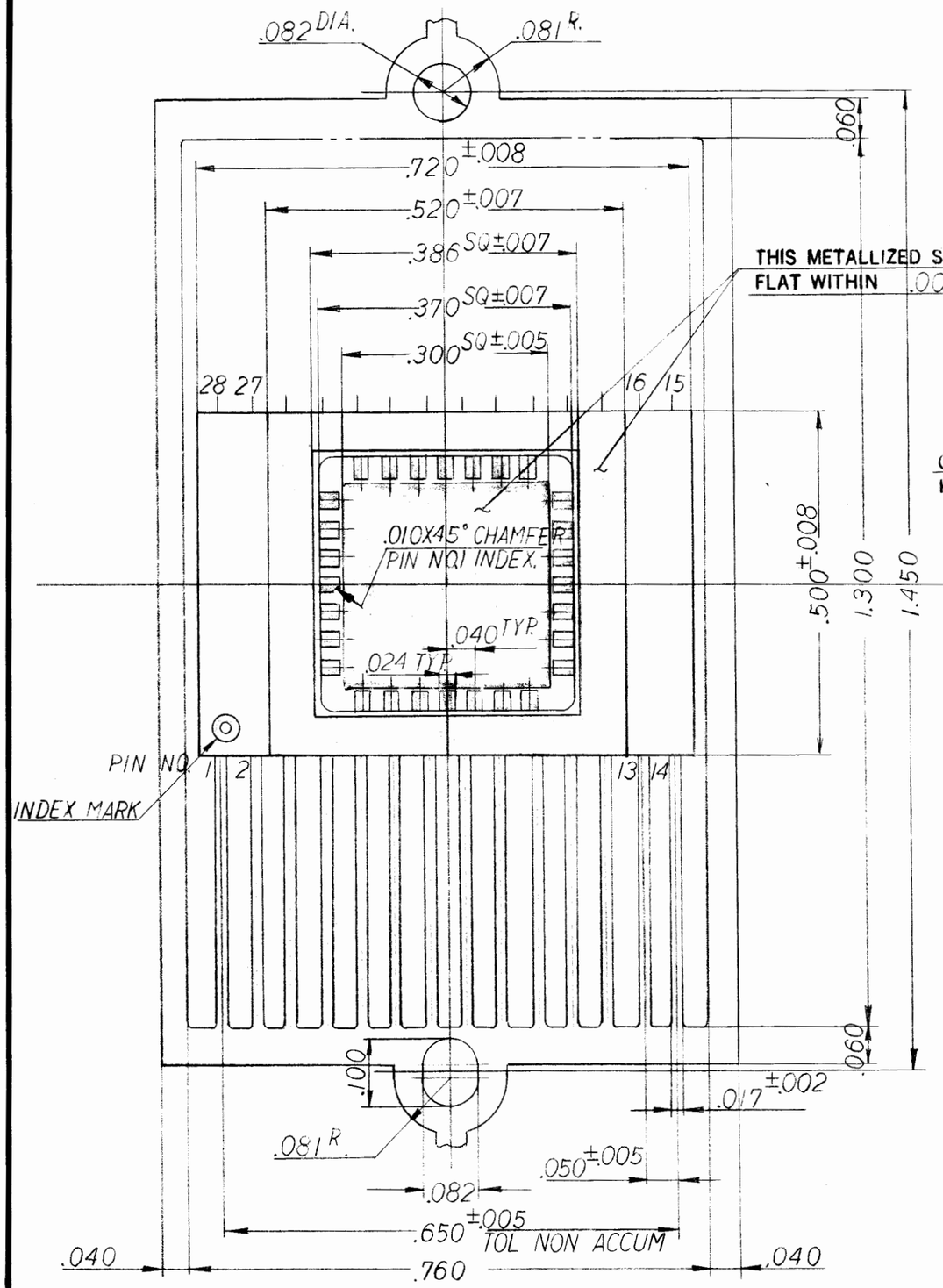
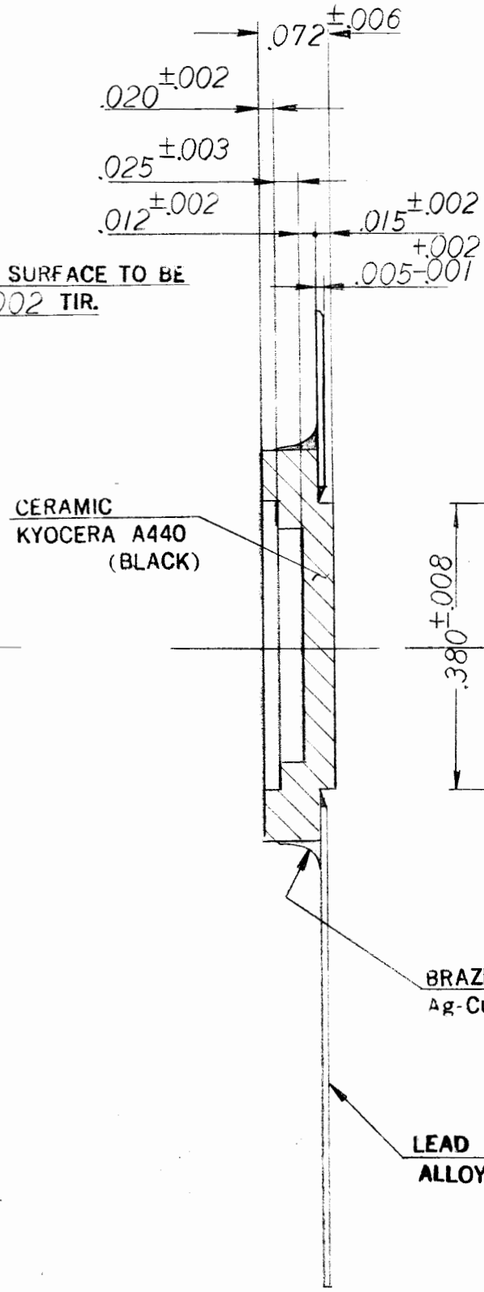
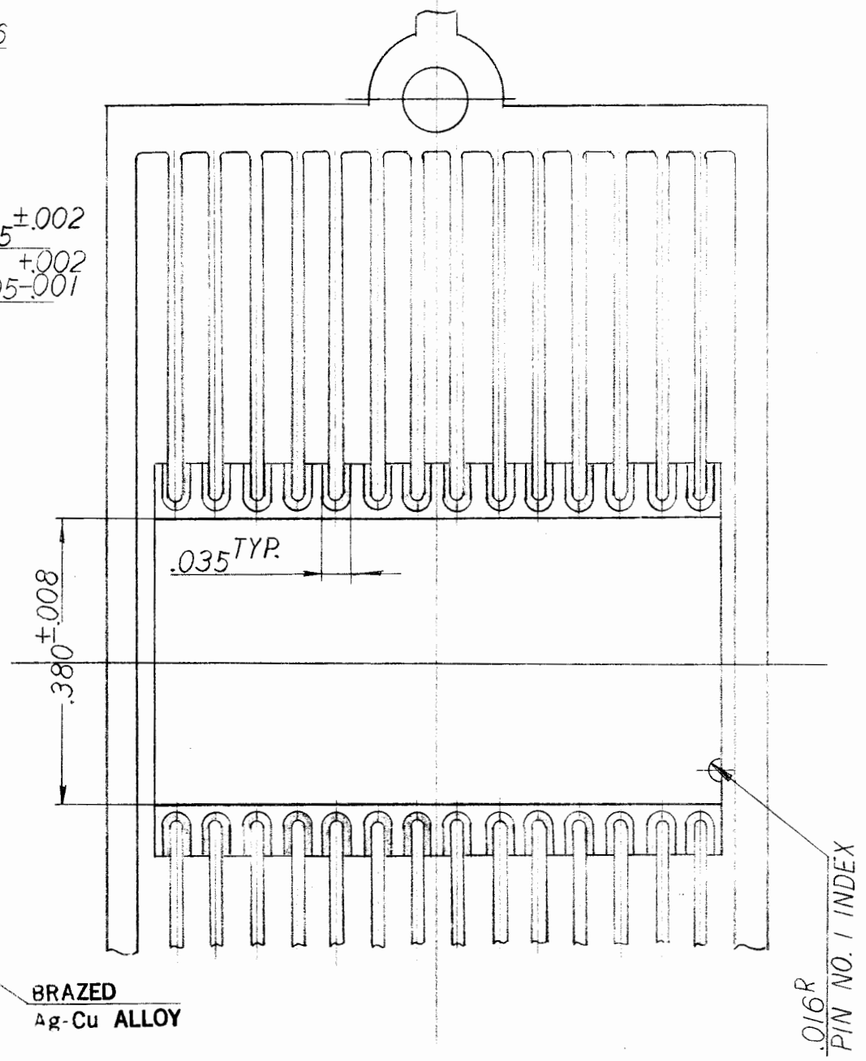


THIS METALLIZED SURFACE TO BE FLAT WITHIN .002 TIR.





NOTES:
1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. LEAD RESISTANCE : 0.25 Ω MAX.
3. SEAL AREA TO BE METALLIZED.
4. DIE ATTACH AREA TO BE METALLIZED.
5. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.

S=0
FB028N401-1 D=0

MODIFICATIONS					
CHANGE	DATE	DRAWN	CHECKED	APPROVED	

NAME: 28 LEAD FLAT PACKAGE		TOLERANCES: UNLESS OTHERWISE SPECIFIED	DRAWN: H. Horinaketa / CHECKED: T. Tatsuoka
SCALE: 5 : 1	MATERIAL: AS INDICATED	±1.0% N.L.T. ±.005	APPROVED: / DATE: JUL.27.83
KYOCERA CORPORATION KYOTO JAPAN			DWG.NO. KD-83401